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HYBRID THICK AND THIN FILM MICROCIRCUITS

A Report Bibliography

by

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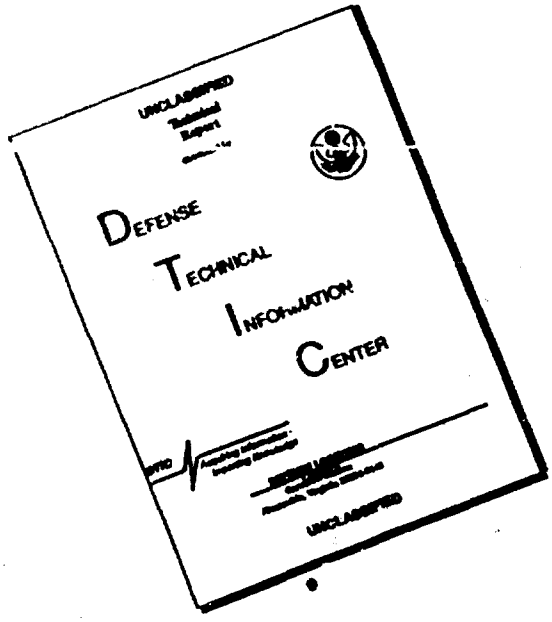

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INTRODUCTION

This report bibliography has been prepared in response to a request for information on hybrid thick film circuits. In view of the fact that this area of hybrids is growing as well as the thin film hybrid area, it was decided to compile on both types and make the bibliography more useful.

The report bibliography covers the time span from 1966 to the present and is arranged in alphabetic sequence for easy reference checking. A total of 63 references were found in the literature and were selected on the basis of having the subject descriptor "hybrid" in the title. Undoubtedly, additional references on the subject occur in the literature but could not be located immediately because they lacked the term "hybrid" in the title.

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